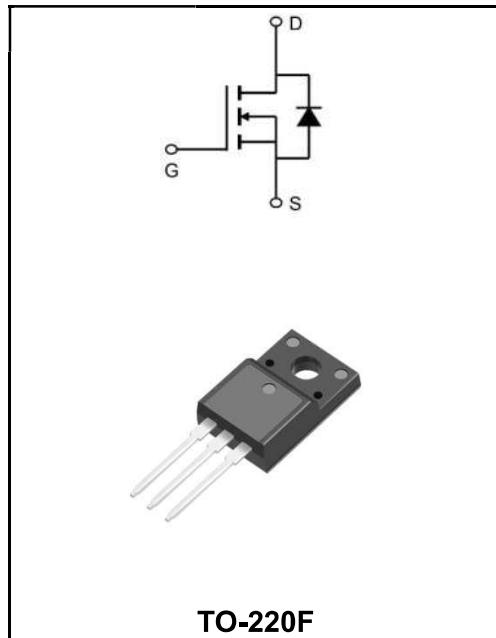


60V N-CHANNEL ENHANCEMENT MODE MOSFET
MAIN CHARACTERISTICS

| | |
|--------------------------------------|----------------------|
| I_D | 60A |
| V_{DSS} | 60V |
| $R_{DS(on)}\text{-typ}(@V_{GS}=10V)$ | < 15mΩ (Type: 11 mΩ) |


Application

- ◆ Battery protection
- ◆ Load switch
- ◆ Uninterruptible power supply

Product Specification Classification

| Part Number | Package | Marking | Pack |
|-------------|---------|-------------------|--------------|
| YFW60N06AF | TO-220F | YFW 60N06AF XXXXX | 1000PCS/Tape |

Maximum Ratings at $T_c=25^\circ C$ unless otherwise specified

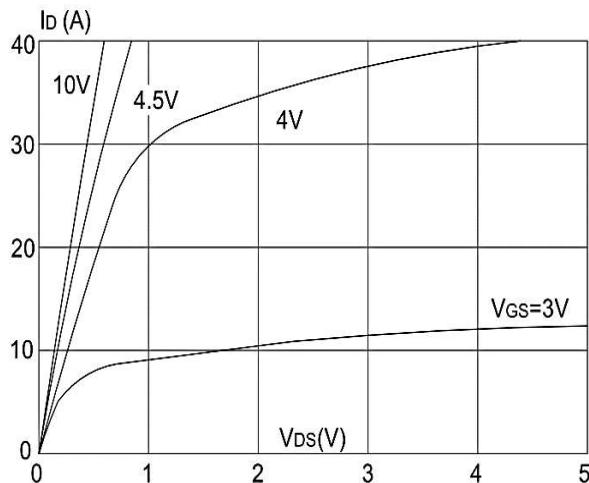
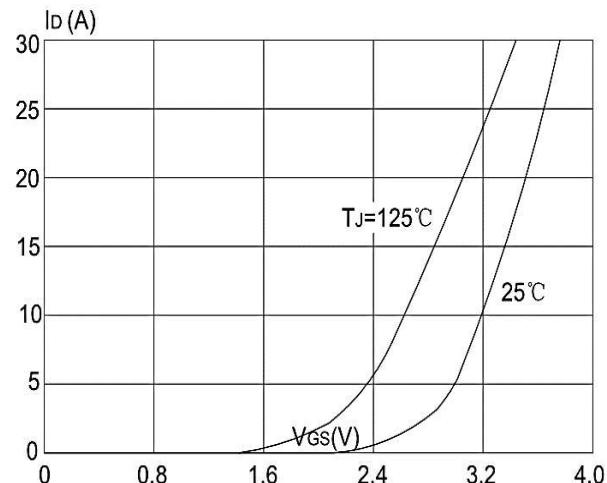
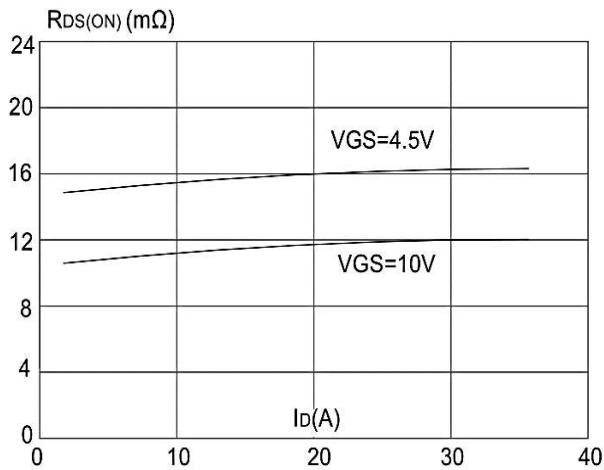
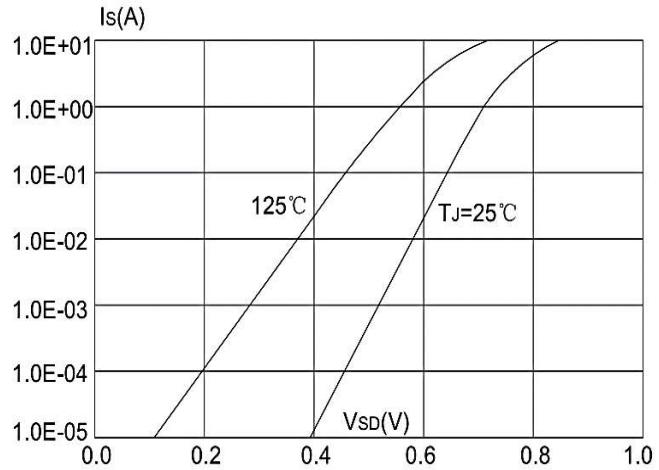
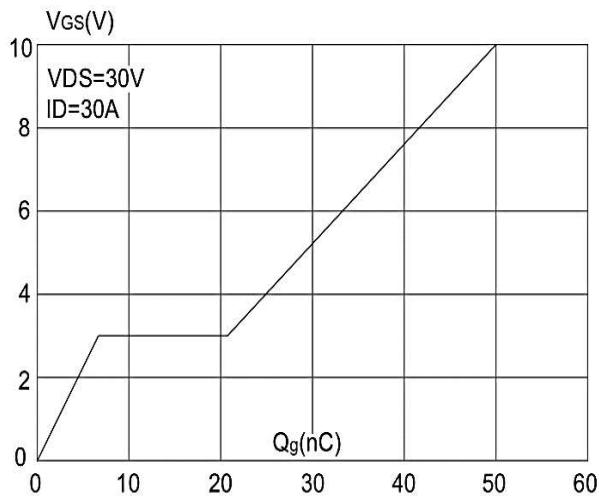
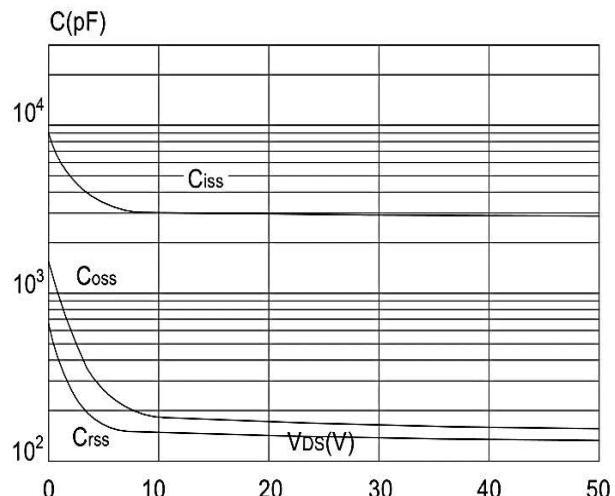
| Characteristics | Symbols | Value | Units |
|--|-----------------|-------------|-------|
| Drain-Source Voltage | V_{DS} | 60 | V |
| Gate - Source Voltage | V_{GS} | ± 20 | V |
| Continuous Drain Current, $V_{GS} @ 10V^1$ @ $T_c=25^\circ C$ | I_D | 60 | A |
| Continuous Drain Current, $V_{GS} @ 10V^1$ @ $T_c=100^\circ C$ | I_D | 35 | A |
| Pulsed Drain Current ² | I_{DM} | 180 | A |
| Single Pulse Avalanche Energy ³ | E_{AS} | 39.2 | mJ |
| Avalanche Current | I_{AS} | 38 | A |
| Power Dissipation ⁴ @ $T_c=25^\circ C$ | P_D | 45 | W |
| Storage Temperature Range | T_{STG} | -55 to +150 | °C |
| Operating Junction Temperature Range | T_J | -55 to +150 | °C |
| Thermal Resistance Junction-Ambient ¹ | $R_{\theta JA}$ | 62.5 | °C/W |
| Thermal Resistance Junction-Case ¹ | $R_{\theta JC}$ | 2.8 | °C/W |

Maximum Ratings at Tc=25°C unless otherwise specified

| Characteristics | Test Condition | Symbols | Min | Typ | Max | Units |
|--|---|------------------------|------------|------------|------------|--------------|
| Drain-Source Breakdown Voltage | V _{GS} =0V, I _D =250uA | BV _{DSS} | 60 | 65 | - | V |
| BVDSS Temperature Coefficient | Reference to 25°C , I _D =1mA | ΔBV _{DSS/ΔTJ} | - | 0.057 | - | V/°C |
| Static Drain-Source On-Resistance ² | V _{GS} =10V, I _D =20A | R _{DS(ON)} | - | 11 | 15 | mΩ |
| | V _{GS} =4.5V, I _D =10A | | - | 16 | 20 | |
| Gate -Threshold Voltage | V _{DS} =V _{GS} , I _D =250uA | V _{GS(th)} | 1.2 | 1.8 | 2.5 | V |
| V _{GS(th)} Temperature Coefficient | | ΔV _{GS(th)} | - | -5.68 | - | mV/°C |
| Drain -Source Leakage Current | V _{DS} =48V , V _{GS} =0V , T _J =25°C | I _{DSS} | - | - | 1 | μA |
| | | | - | - | 5 | |
| Gate-Source Leakage Current | V _{GS} =±20V, V _{DS} =0V | I _{GSS} | - | - | ±100 | nA |
| Forward Transconductance | V _{DS} =5V, I _D =15A | g _{FS} | - | 45 | - | S |
| Gate Resistance | V _{DS} =0V , V _{GS} =0V , f=1MHz | R _G | - | 1.7 | - | Ω |
| Total Gate Charge(4.5V) | V _{DS} =48V V _{GS} =4.5V I _D =15A | Q _g | - | 19.3 | - | nC |
| Gate-Source Charge | | Q _{gs} | - | 7.1 | - | |
| Gate-Drain Charge | | Q _{gd} | - | 7.6 | - | |
| Turn-on delay time | V _{DD} =30V V _{GS} =10V R _G =3.3Ω I _D =15A | t _{d(on)} | - | 7.2 | - | ns |
| Rise Time | | T _r | - | 50 | - | |
| Turn-Off Delay Time | | t _{d(OFF)} | - | 36.4 | - | |
| Fall Time | | t _f | - | 7.6 | - | |
| Input Capacitance | V _{DS} =15V V _{GS} =0V f=1.0MHz | C _{iss} | - | 2423 | - | pF |
| Output Capacitance | | C _{oss} | - | 145 | - | |
| Reverse Transfer Capacitance | | C _{rss} | - | 97 | - | |
| Continuous Source Current ^{1,5} | V _G =V _D =0V , Force Current | I _S | - | - | 35 | A |
| Pulsed Source Current ^{2,5} | | I _{SM} | - | - | 80 | A |
| Diode Forward Voltage ² | V _{GS} =0V , I _S =A , T _J =25°C | V _{SD} | - | - | 1 | V |
| Reverse Recovery Time | I _F =15A , dI/dt=100A/μs , T _J =25°C | t _{rr} | - | 16.3 | - | nS |
| Reverse Recovery Charge | | Q _{rr} | - | 11 | - | nC |

Note :

1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
2. The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
3. The EAS data shows Max. rating . The test condition is VDD=25V,VGS=10V,L=0.1mH,IAS=38A
4. The power dissipation is limited by 150°C junction temperature
5. The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation

Ratings and Characteristic Curves
Typical Characteristics

Figure 1: Output Characteristics

Figure 2: Typical Transfer Characteristics

Figure 3: On-resistance vs. Drain Current

Figure 4: Body Diode Characteristics

Figure 5: Gate Charge Characteristics

Figure 6: Capacitance Characteristics

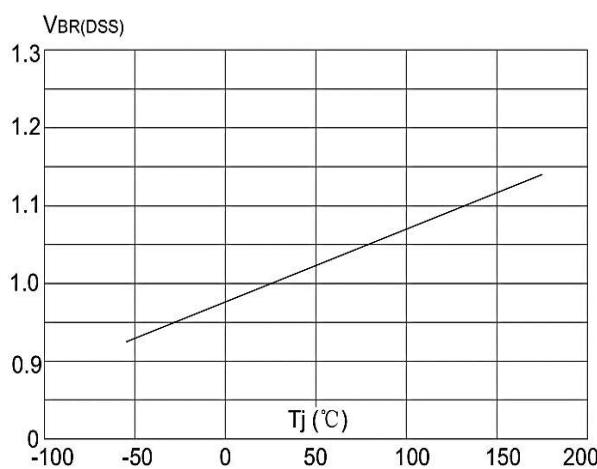
Ratings and Characteristic Curves


Figure 7: Normalized Breakdown Voltage vs Junction Temperature

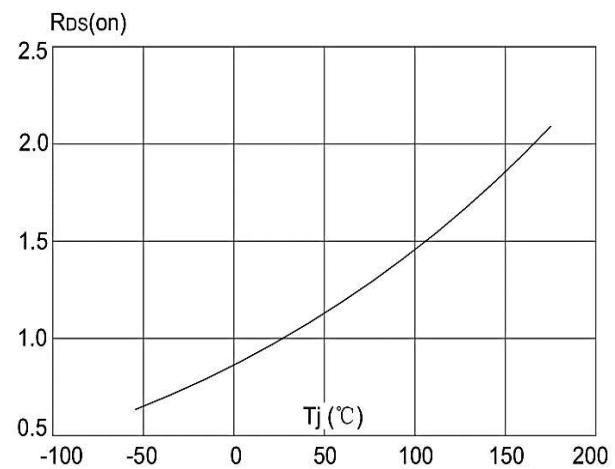


Figure 8: Normalized on Resistance vs. Junction Temperature

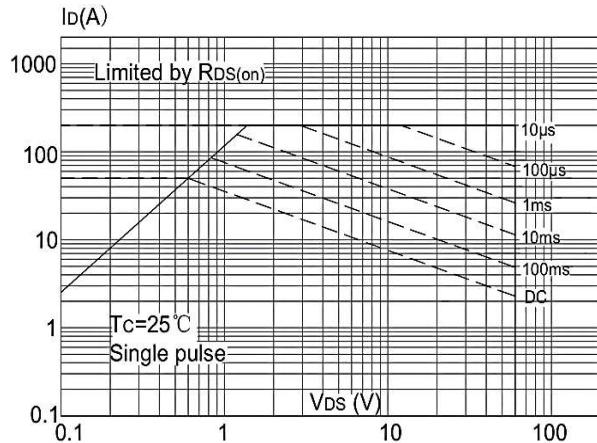


Figure 9: Maximum Safe Operating Area

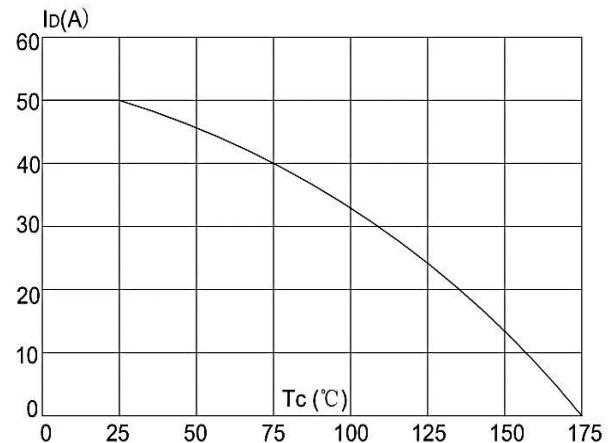


Figure 10: Maximum Continuous Drain Current vs. Ambient Temperature

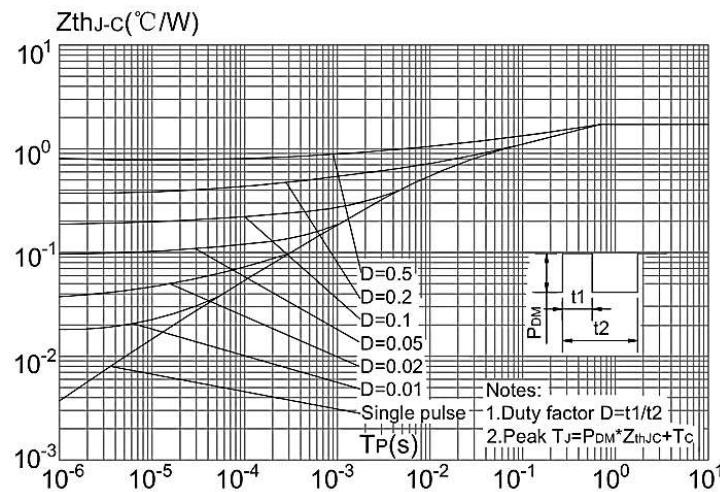
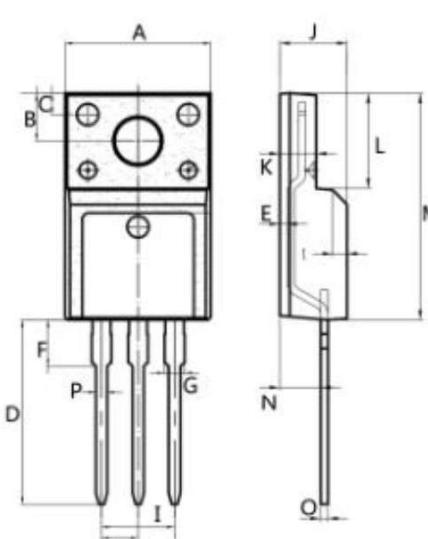


Figure 11: Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

Package Outline Dimensions Millimeters

TO-220F



| Dim. | Min. | Max. |
|------|----------|-------|
| A | 9.95 | 10.25 |
| B | 2.95 | 3.25 |
| C | 1.25 | 1.45 |
| D | 12.95 | 13.25 |
| E | 0.50 | 0.65 |
| F | 3.1 | 3.3 |
| G | 1.30 | 1.45 |
| H | Typ 2.54 | |
| I | Typ 5.08 | |
| J | 4.60 | 4.75 |
| K | 2.50 | 2.65 |
| L | 6.35 | 6.55 |
| M | 15.4 | 16.0 |
| N | 2.75 | 3.05 |
| O | 0.48 | 0.52 |
| P | 0.76 | 0.84 |

All Dimensions in millimeter